

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





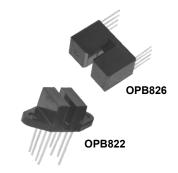


OPB822S, OPB822SD OPB826S, OPB826SD

Features:

- Non-contact switching
- Single or double apertures for high resolution
- Choice of slot widths
- Choice of side-by-side or over/under dual channels
- Choice of electrical outputs





Description:

Each **OPB822** and **OPB826** slotted switch consists of two infrared emitting diodes and two NPN silicon phototransistors mounted on opposite sides of a 0.090" (2.29 mm) wide slot **(OPB822)** or a 0.100" (2.54 mm) wide slot **(OPB826)**.

OPB822 uses an side-by-side mounting configuration, while **OPB826** uses an over/under mounting configuration. **OPB822S** has 0.01" by 0.04" (0.25 mm x 1.02 mm) apertures in front of both phototransistors while the **OPB822SD** has the aperture in front of both phototransistors and both emitters. The **OPB826S** has 0.04" by 0.04" (1.02 mm x 1.02 mm) apertures in front of both phototransistors while the **OPB826SD** has the aperture in front of both phototransistors and both emitters.

Dual channels enable direction of travel sensing, with the low-cost plastic housing reduces possible interference from ambient light and provides protection from dust and dirt.

Phototransistor switching occurs when an opaque object passes through the device slot.

For information on encoder design, see Application Bulletin 203 at:

Custom electrical, wire and cabling and connectors are available. Contact your local representative or OPTEK for more information.

Applications:

- Encoders
- · Non-contact object sensing
- Assembly line automation
- Machine automation
- Equipment security
- Machine safety

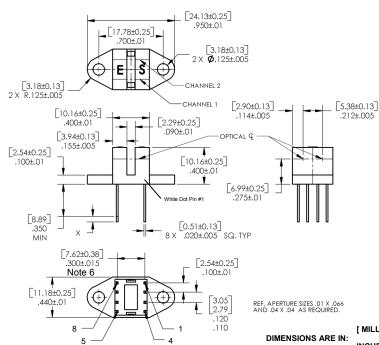
Part	LED Peak		Slot Width /	Aperture Emitter/	Lead Length /
Number	Wavelength	Sensor	Depth	Sensor	Spacing
OPB822S	Dual	Dual	0.09" /	None / 0.01"	0.35" /
OPB822SD	935 nm	Transistor	0.30"	0.01" / 0.01"	0.30"
OPB826S	Dual	Dual	0.10" /	NA / 0.04"	0.20" /
OPB826SD	890 nm	Transistor	0.42"	0.04" / 0.04"	0.74"

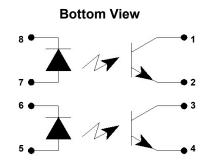


OPB822S, OPB822SD OPB826S, OPB826SD



OPB822

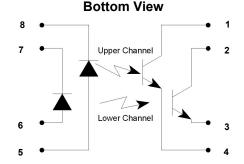




Pin#	Description	Pin#	Description
8	Cathode-1	1	Collector-1
7	Anode-1	2	Emitter-1
6	Cathode-2	3	Collector-2
5	Anode-2	4	Emitter-2

[MILLIMETERS] INCHES

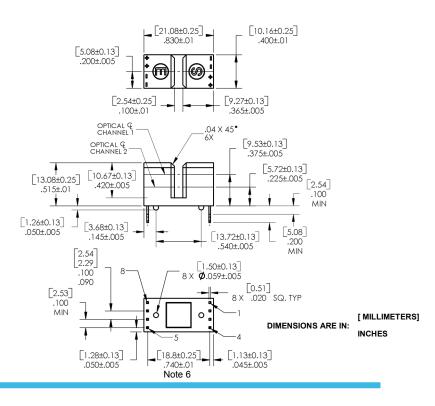
OPB826



Pin#	Description	Pin#	Description
8	Cathode-1	1	Collector-1
7	Cathode-2	2	Collector-2
6	Anode-2	3	Emitter-2
5	Anode-1	4	Emitter-1

CONTAINS POLYSULFONE

To avoid stress cracking, we suggest using ND Industries' Vibra-Tite for thread-locking. Vibra-Tite evaporates fast without causing structural failure in OPTEK's molded plastics.



General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

OPB822S, OPB822SD OPB826S, OPB826SD



Absolute Maximum Ratings (T_A = 25° C unless otherwise noted)

Storage & Operating Temperature Range	-40° C to +85° C
Lead Soldering Temperature [1/16 inch (1.6mm) from the case for 5 sec. with soldering iron] (1)	240°C

Input Diode

Forward DC Current	
OPB822S, OPB822SD	50 mA
OPB826S, OPB826SD	40 mA
Peak Forward Current (1 μs pulse width, 300 pps)	1 A
Reverse DC Voltage	2 V
Power Dissipation ⁽²⁾	100 mW

Output Phototransistor

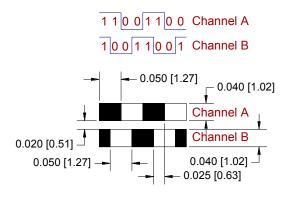
Collector-Emitter Voltage	30 V
Emitter-Collector Voltage	5 V
Collector DC Current	30 mA
Power Dissipation ⁽²⁾	100 mW

Notes:

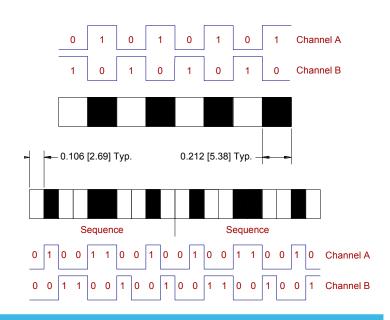
- (1) RMA flux is recommended. Duration can be extended to 10 seconds maximum when flow soldering.
- (2) Derate linearly 1.67 mW/°C above 25° C.
- (3) Methanol or isopropanol are recommended as cleaning agents. Plastic housing is soluble in chlorinated hydrocarbons and ketones. <u>Spray and wipe; do not submerge</u>.
- (4) Derate linearly 3.33 mW/°C above 25° C.
- (5) All parameters tested using pulse techniques.
- (6) Feature controlled at body.

Encoder Sequence for OPB822

Encoder Sequence for OPB826



For information on encoder design, see Application Bulletin 203 at: http://www.optekinc.com/pdf/App_Note_203.pdf



OPB822S, OPB822SD OPB826S, OPB826SD



Electrical Characteristics (OPB822, OPB826) (T_A = 25°C unless otherwise noted)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
nput Diod	e (see OP14O for OPB822 or OP266 for OPB	826 for	additic	nal info	rmation)	
V _F	Forward Voltage	-	-	1.7	V	I _F = 20 mA
I _R	Reverse Current	-	-	100	μΑ	V _R = 2 V
Output Pho	ototransistor (see OP550 for OPB822 or OP	506 for	OPB826	for add	litional inf	ormation)
V _{(BR)(CEO)}	Collector-Emitter Breakdown Voltage	30	-	-	V	I _C = 1 mA
V _{(BR)(ECO)}	Emitter-Collector Breakdown Voltage	5	-	-	V	Ι _Ε = 100 μΑ
I _{CEO}	Collector-Emitter Leakage Current	-	-	100	nA	$V_{CE} = 10 \text{ V}, I_F = 0, E_E = 0$
Coupled		<u> </u>		<u>I</u>	Į.	
I _{C(ON)}	On-State Collector Current OPB822S OPB822SD OPB826S OPB826SD	250 100 250 100	- - - -	- - -	μΑ μΑ μΑ μΑ	$V_{CE} = 5 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 5 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 10 \text{ V, } I_F = 20 \text{ mA}$ $V_{CE} = 10 \text{ V, } I_F = 20 \text{ mA}$
V _{CE(SAT)}	Collector-Emitter Saturation Voltage OPB822S OPB822SD OPB826S OPB826SD	1 1 1	- - -	0.4 0.4 0.4 0.4	V V V	$I_C = 125 \mu A$, $I_F = 20 mA$ $I_C = 50 \mu A$, $I_F = 20 mA$ $I_C = 125 \mu A$, $I_F = 20 mA$ $I_C = 50 \mu A$, $I_F = 20 mA$
I _{CX1}	Crosstalk OPB822D, OPB822SD OPB826S OPB826SD	- - -	- - -	250 20 10	μΑ	I _{F1} = 0 mA, I _{F2} = 20 mA, V _{CE} = 10 V

Notes:

⁽¹⁾ All parameters tested using pulse techniques.